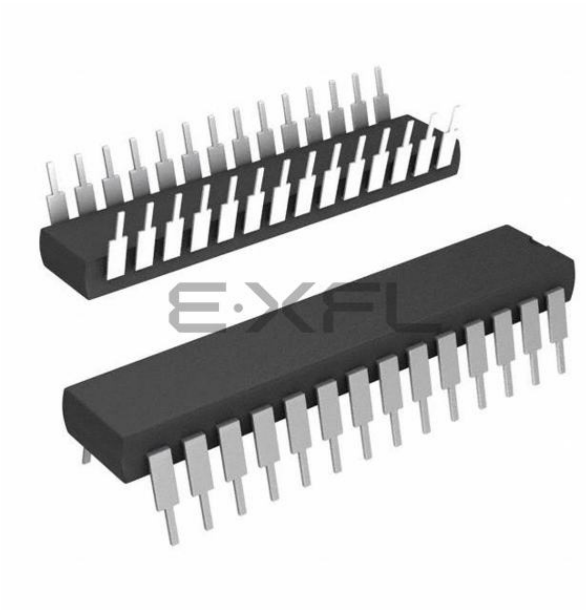


Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16ka302-i-sp

4.3.2 DATA ACCESS FROM PROGRAM MEMORY AND DATA EEPROM MEMORY USING TABLE INSTRUCTIONS

The `TBLRDL` and `TBLWTL` instructions offer a direct method of reading or writing the lower word of any address within the program memory without going through data space. It also offers a direct method of reading or writing a word of any address within data EEPROM memory. The `TBLRDH` and `TBLWTH` instructions are the only method to read or write the upper 8 bits of a program space word as data.

> **Note:** The `TBLRDH` and `TBLWTH` instructions are not used while accessing data EEPROM memory.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit word-wide address spaces, residing side by side, each with the same address range. `TBLRDL` and `TBLWTL` access the space which contains the least significant data word, and `TBLRDH` and `TBLWTH` access the space which contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from program space. Both function as either byte or word operations.

1. `TBLRDL` (Table Read Low): In Word mode, it maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).

   In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when byte select is '`1`'; the lower byte is selected when it is '`0`'.

2. `TBLRDH` (Table Read High): In Word mode, it maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom' byte, will always be '`0`'.

   In Byte mode, it maps the upper or lower byte of the program word to D<7:0> of the data address, as above. Note that the data will always be '`0`' when the upper 'phantom' byte is selected (Byte Select = `1`).

REGISTER 8-14: IEC3: INTERRUPT ENABLE CONTROL REGISTER 3

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
—	RTCIE	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0
—	—	—	—	—	MI2C2IE	SI2C2IE	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14 **RTCIE:** Real-Time Clock and Calendar Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 13-3 **Unimplemented:** Read as ‘0’

bit 2 **MI2C2IE:** Master I2C2 Event Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 1 **SI2C2IE:** Slave I2C2 Event Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 0 **Unimplemented:** Read as ‘0’

NOTES:

10.3 Ultra Low-Power Wake-up

The Ultra Low-Power Wake-up (ULPWU) on pin, RB0, allows a slow falling voltage to generate an interrupt without excess current consumption.

To use this feature:

1. Charge the capacitor on RB0 by configuring the RB0 pin to an output and setting it to '1'.
2. Stop charging the capacitor by configuring RB0 as an input.
3. Discharge the capacitor by setting the ULPEN and ULPSINK bits in the ULPWCON register.
4. Configure Sleep mode.
5. Enter Sleep mode.

When the voltage on RB0 drops below V_{IL}, the device wakes up and executes the next instruction.

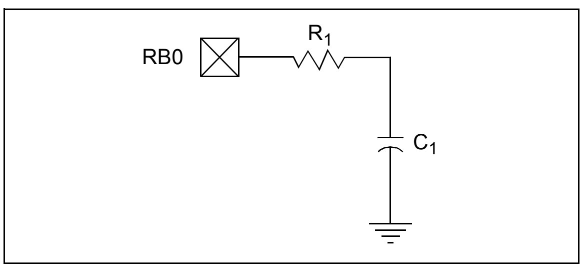
This feature provides a low-power technique for periodically waking up the device from Sleep mode.

The time-out is dependent on the discharge time of the RC circuit on RB0.

When the ULPWU module wakes the device from Sleep mode, the ULPWUIF bit (IFS5<0>) is set. Software can check this bit upon wake-up to determine the wake-up source. See Example 10-3 for initializing the ULPWU module.

A series resistor, between RB0 and the external capacitor, provides overcurrent protection for the RB0/AN0/ULPWU pin and enables software calibration of the time-out (see Figure 10-1).

FIGURE 10-1: SERIES RESISTOR



A timer can be used to measure the charge time and discharge time of the capacitor. The charge time can then be adjusted to provide the desired delay in Sleep. This technique compensates for the affects of temperature, voltage and component accuracy. The peripheral can also be configured as a simple, programmable Low-Voltage Detect (LVD) or temperature sensor.

EXAMPLE 10-3: ULTRA LOW-POWER WAKE-UP INITIALIZATION

```
//*******************************
// 1. Charge the capacitor on RB0
//*******************************
    TRISBbits.TRISB0 = 0;
    LATBbits.LATB0 = 1;
    for(i = 0; i < 10000; i++) Nop();
//*****************************
//2. Stop Charging the capacitor
//   on RB0
//*****************************
    TRISBbits.TRISB0 = 1;
//*****************************
//3. Enable ULPWU Interrupt
//*****************************
IFS5bits.ULPWUIF = 0;
IEC5bits.ULPWUIE = 1;
IPC21bits.ULPWUIP = 0x7;
//*****************************
//4. Enable the Ultra Low Power
//   Wakeup module and allow
//   capacitor discharge
//*****************************
    ULPWCONbits.ULPEN = 1;
    ULPWCONbit.ULPSINK = 1;
//*****************************
//5. Enter Sleep Mode
//*****************************
    Sleep();
//for sleep, execution will
//resume here
```


REGISTER 10-3: ULPWCON: ULPWU CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0
ULPEN	—	ULPSIDL	—	—	—	—	ULPSINK
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ULPEN:** ULPWU Module Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **ULPSIDL:** ULPWU Stop in Idle Select bit
1 = Discontinues module operation when the device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-9 **Unimplemented:** Read as ‘0’

bit 8 **ULPSINK:** ULPWU Current Sink Enable bit
1 = Current sink is enabled
0 = Current sink is disabled

bit 7-0 **Unimplemented:** Read as ‘0’

15.2 Compare Operations

In Compare mode (Figure 15-1), the output compare module can be configured for single-shot or continuous pulse generation. It can also repeatedly toggle an output pin on each timer event.

To set up the module for compare operations:

1. Calculate the required values for the OCxR and (for Double Compare modes) OCxRS Duty Cycle registers:
   a) Determine the instruction clock cycle time. Take into account the frequency of the external clock to the timer source (if one is used) and the timer prescaler settings.
   b) Calculate the time to the rising edge of the output pulse relative to the timer start value (0000h).
   c) Calculate the time to the falling edge of the pulse, based on the desired pulse width and the time to the rising edge of the pulse.
2. Write the rising edge value to OCxR and the falling edge value to OCxRS.
3. For Trigger mode operations, set OCTRIG to enable Trigger mode. Set or clear TRIGMODE to configure the trigger operation and TRIGSTAT to select a hardware or software trigger. For Synchronous mode, clear OCTRIG.
4. Set the SYNCSEL<4:0> bits to configure the trigger or synchronization source. If free-running timer operation is required, set the SYNCSELx bits to '00000' (no Sync/trigger source).
5. Select the time base source with the OCTSEL<2:0> bits. If the desired clock source is running, set the OCTSEL<2:0> bits before the output compare module is enabled for proper synchronization with the desired clock source. If necessary, set the TON bit for the selected timer which enables the compare time base to count. Synchronous mode operation starts as soon as the synchronization source is enabled; Trigger mode operation starts after a trigger source event occurs.
6. Set the OCM<2:0> bits for the appropriate compare operation ('0xx').

For 32-bit cascaded operation, these steps are also necessary:

1. Set the OC32 bits for both registers (OCyCON2<8> and (OCxCON2<8>). Enable the even numbered module first to ensure the modules will start functioning in unison.
2. Clear the OCTRIG bit of the even module (OCyCON2), so the module will run in Synchronous mode.
3. Configure the desired output and Fault settings for OCy.
4. Force the output pin for OCx to the output state by clearing the OCTRIS bit.
5. If Trigger mode operation is required, configure the trigger options in OCx by using the OCTRIG (OCxCON2<7>), TRIGSTAT (OCxCON2<6>) and SYNCSELx (OCxCON2<4:0>) bits.
6. Configure the desired Compare or PWM mode of operation (OCM<2:0>) for OCy first, then for OCx.

Depending on the output mode selected, the module holds the OCx pin in its default state and forces a transition to the opposite state when OCxR matches the timer. In Double Compare modes, OCx is forced back to its default state when a match with OCxRS occurs. The OCxIF interrupt flag is set after an OCxR match in Single Compare modes and after each OCxRS match in Double Compare modes.

Single-shot pulse events only occur once, but may be repeated by simply rewriting the value of the OCxCON1 register. Continuous pulse events continue indefinitely until terminated.

REGISTER 17-2: I2CxSTAT: I2Cx STATUS REGISTER (CONTINUED)

bit 4 **P:** Stop bit

1 = Indicates that a Stop bit has been detected last
0 = Stop bit was not detected last
Hardware is set or cleared when a Start, Repeated Start or Stop is detected.

bit 3 **S:** Start bit

1 = Indicates that a Start (or Repeated Start) bit has been detected last
0 = Start bit was not detected last
Hardware is set or clear when a Start, Repeated Start or Stop is detected.

bit 2 **R/$\overline{\text{W}}$:** Read/$\overline{\text{Write}}$ Information bit (when operating as I^2C slave)

1 = Read – indicates data transfer is output from the slave
0 = Write – indicates data transfer is input to the slave
Hardware is set or clear after the reception of an I^2C device address byte.

bit 1 **RBF:** Receive Buffer Full Status bit

1 = Receive is complete, I2CxRCV is full
0 = Receive is not complete, I2CxRCV is empty
Hardware is set when I2CxRCV is written with a received byte; hardware is clear when the software reads I2CxRCV.

bit 0 **TBF:** Transmit Buffer Full Status bit

1 = Transmit is in progress, I2CxTRN is full
0 = Transmit is complete, I2CxTRN is empty
Hardware is set when the software writes to I2CxTRN; hardware is clear at the completion of data transmission.

REGISTER 22-2: AD1CON2: A/D CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PVCFG1	PVCFG0	NVCFG0	OFFCAL	BUFREGEN	CSCNA	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BUFS(1)	SMPI4	SMPI3	SMPI2	SMPI1	SMPI0	BUFM(1)	ALTS
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **PVCFG<1:0>:** Converter Positive Voltage Reference Configuration bits
11 = 4 * Internal V_{BG}(2)
10 = 2 * Internal V_{BG}(3)
01 = External V_{REF}+
00 = AV_{DD}

bit 13 **NVCFG0:** Converter Negative Voltage Reference Configuration bits
1 = External V_{REF}-
0 = AV_{SS}

bit 12 **OFFCAL:** Offset Calibration Mode Select bit
1 = Inverting and non-inverting inputs of channel Sample-and-Hold are connected to AV_{SS}
0 = Inverting and non-inverting inputs of channel Sample-and-Hold are connected to normal inputs

bit 11 **BUFREGEN:** A/D Buffer Register Enable bit
1 = Conversion result is loaded into a buffer location determined by the converted channel
0 = A/D result buffer is treated as a FIFO

bit 10 **CSCNA:** Scan Input Selections for CH0+ S/H Input for MUX A Setting bit
1 = Scans inputs
0 = Does not scan inputs

bit 9-8 **Unimplemented:** Read as ‘0’

bit 7 **BUFS:** Buffer Fill Status bit(1)
1 = A/D is filling the upper half of the buffer; user should access data in the lower half
0 = A/D is filling the lower half of the buffer; user should access data in the upper half

bit 6-2 **SMPI<4:0>:** Sample Rate Interrupt Select bits
11111 = Interrupts at the completion of the conversion for each 32nd sample
11110 = Interrupts at the completion of the conversion for each 31st sample
•
•
•
00001 = Interrupts at the completion of the conversion for every other sample
00000 = Interrupts at the completion of the conversion for each sample

bit 1 **BUFM:** Buffer Fill Mode Select bit(1)
1 = Starts filling the buffer at address, AD1BUF0, on the first interrupt and AD1BUF(n/2) on the next interrupt (Split Buffer mode)
0 = Starts filling the buffer at address, ADCBUF0, and each sequential address on successive interrupts (FIFO mode)

Note 1: This is only applicable when the buffer is used in FIFO mode (BUFREGEN = 0). In addition, BUFS is only used when BUFM = 1.
2: The voltage reference setting will not be within the specification with V_{DD} below 4.5V.
3: The voltage reference setting will not be within the specification with V_{DD} below 2.3V.

TABLE 22-4: NUMERICAL EQUIVALENTS OF VARIOUS RESULT CODES: 10-BIT FRACTIONAL FORMATS

VIN/VREF	10-Bit Differential Output Code (11-bit result)	16-Bit Fractional Format/ Equivalent Decimal Value		16-Bit Signed Fractional Format/ Equivalent Decimal Value	
+1023/1024	011 1111 1111	1111 1111 1100 0000	0.999	0111 1111 1110 0000	0.999
+1022/1024	011 1111 1110	1111 1111 1000 0000	0.998	0111 1111 1000 0000	0.998
• • •					
+1/1024	000 0000 0001	0000 0000 0100 0000	0.001	0000 0000 0010 0000	0.001
0/1024	000 0000 0000	0000 0000 0000 0000	0.000	0000 0000 0000 0000	0.000
-1/1024	101 1111 1111	0000 0000 0000 0000	0.000	1111 1111 1110 0000	-0.001
• • •					
-1023/1024	100 0000 0001	0000 0000 0000 0000	0.000	1000 0000 0010 0000	-0.999
-1024/1024	100 0000 0000	0000 0000 0000 0000	0.000	1000 0000 0000 0000	-1.000

25.3 Pulse Generation and Delay

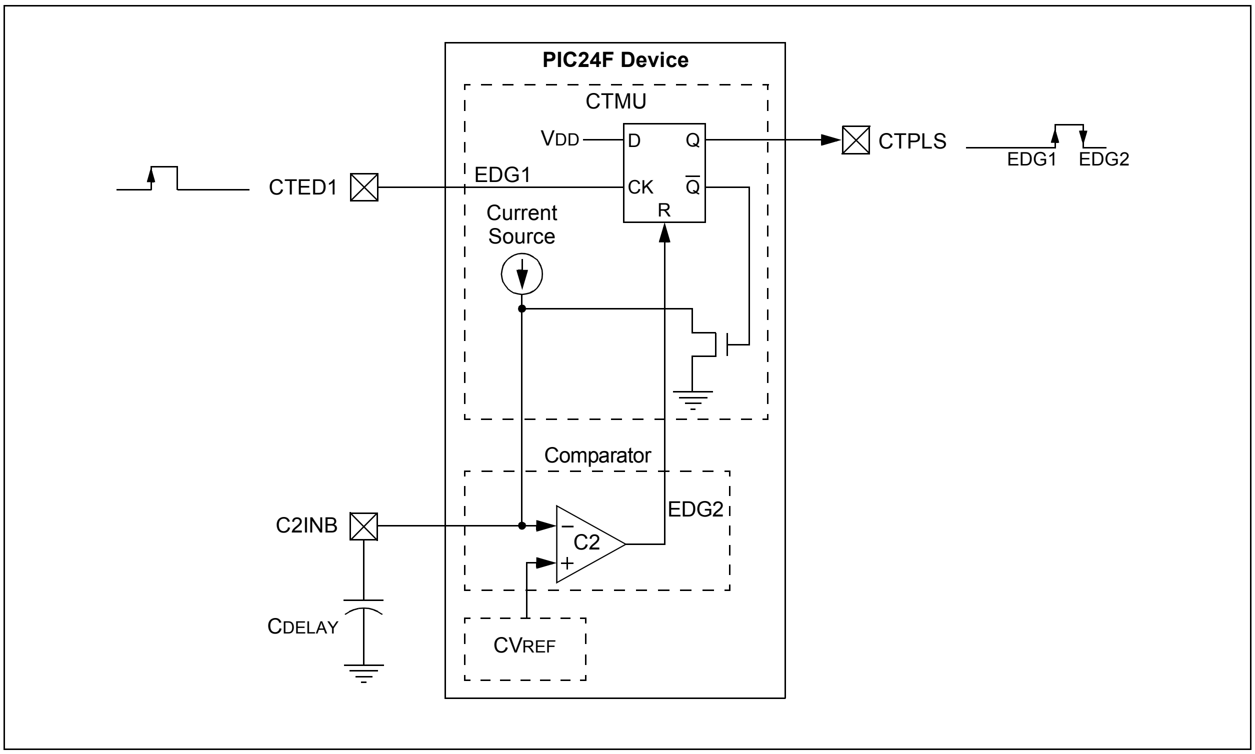
The CTMU module can also generate an output pulse with edges that are not synchronous with the device's system clock. More specifically, it can generate a pulse with a programmable delay from an edge event input to the module.

When the module is configured for pulse generation delay by setting the TGEN bit (CTMUCON<12>), the internal current source is connected to the B input of Comparator 2. A capacitor (C_{DELAY}) is connected to the Comparator 2 pin, C2INB, and the Comparator Voltage Reference, CV_{REF}, is connected to C2INA. CV_{REF} is then configured for a specific trip point. The module begins to charge C_{DELAY} when an edge event is detected. While CV_{REF} is greater than the voltage on C_{DELAY}, CTPLS is high.

When the voltage on C_{DELAY} equals CV_{REF}, CTPLS goes low. With Comparator 2 configured as the second edge, this stops the CTMU from charging. In this state event, the CTMU automatically connects to ground. The IDISSEN bit doesn't need to be set and cleared before the next CTPLS cycle.

Figure 25-3 illustrates the external connections for pulse generation, as well as the relationship of the different analog modules required. While CTED1 is shown as the input pulse source, other options are available. A detailed discussion on pulse generation with the CTMU module is provided in the "*PIC24F Family Reference Manual*".

FIGURE 25-3: TYPICAL CONNECTIONS AND INTERNAL CONFIGURATION FOR PULSE DELAY GENERATION



REGISTER 26-8: FDS: DEEP SLEEP CONFIGURATION REGISTER

R/P-1	R/P-1	U-0	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
DSWDTEN	DSBOREN	—	DSWDTOSC	DSWDTPS3	DSWDTPS2	DSWDTPS1	DSWDTPS0
bit 7							bit 0

Legend:			
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **DSWDTEN:** Deep Sleep Watchdog Timer Enable bit
1 = DSWDT is enabled
0 = DSWDT is disabled

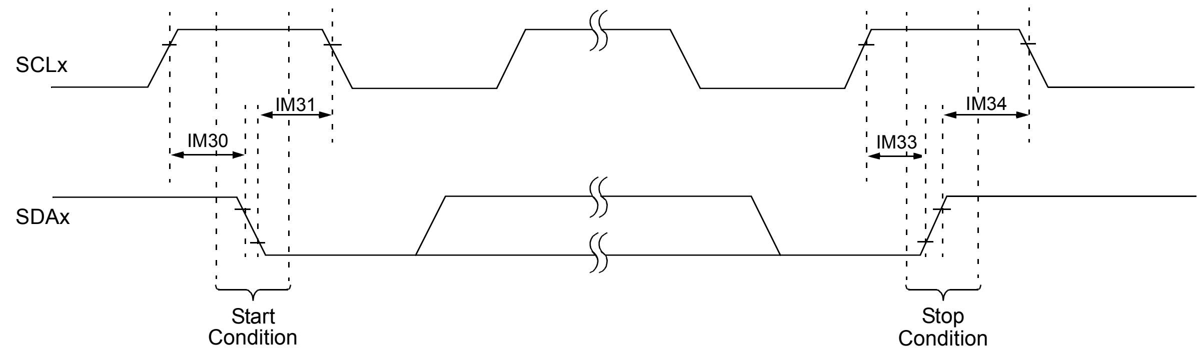
bit 6 **DSBOREN:** Deep Sleep/Low-Power BOR Enable bit
(does not affect operation in non Deep Sleep modes)
1 = Deep Sleep BOR is enabled in Deep Sleep
0 = Deep Sleep BOR is disabled in Deep Sleep

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **DSWDTOSC:** DSWDT Reference Clock Select bit
1 = DSWDT uses LPRC as the reference clock
0 = DSWDT uses SOSC as the reference clock

bit 3-0 **DSWDTPS<3:0>:** Deep Sleep Watchdog Timer Postscale Select bits
The DSWDT prescaler is 32; this creates an approximate base time unit of 1 ms.
1111 = 1:2,147,483,648 (25.7 days) nominal
1110 = 1:536,870,912 (6.4 days) nominal
1101 = 1:134,217,728 (38.5 hours) nominal
1100 = 1:33,554,432 (9.6 hours) nominal
1011 = 1:8,388,608 (2.4 hours) nominal
1010 = 1:2,097,152 (36 minutes) nominal
1001 = 1:524,288 (9 minutes) nominal
1000 = 1:131,072 (135 seconds) nominal
0111 = 1:32,768 (34 seconds) nominal
0110 = 1:8,192 (8.5 seconds) nominal
0101 = 1:2,048 (2.1 seconds) nominal
0100 = 1:512 (528 ms) nominal
0011 = 1:128 (132 ms) nominal
0010 = 1:32 (33 ms) nominal
0001 = 1:8 (8.3 ms) nominal
0000 = 1:2 (2.1 ms) nominal

FIGURE 29-12: I²C™ BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 29-3 for load conditions.

TABLE 29-31: I²C™ BUS START/STOP BIT TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				**Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial) -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	μs	
			400 kHz mode	TCY/2 (BRG + 1)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	μs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	

Note 1: BRG is the value of the I²C™ Baud Rate Generator. Refer to **Section 17.3 "Setting Baud Rate When Operating as a Bus Master"** for details.

2: Maximum pin capacitance = 10 pF for all I²C pins (for 1 MHz mode only).

FIGURE 29-15: I²C™ BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)

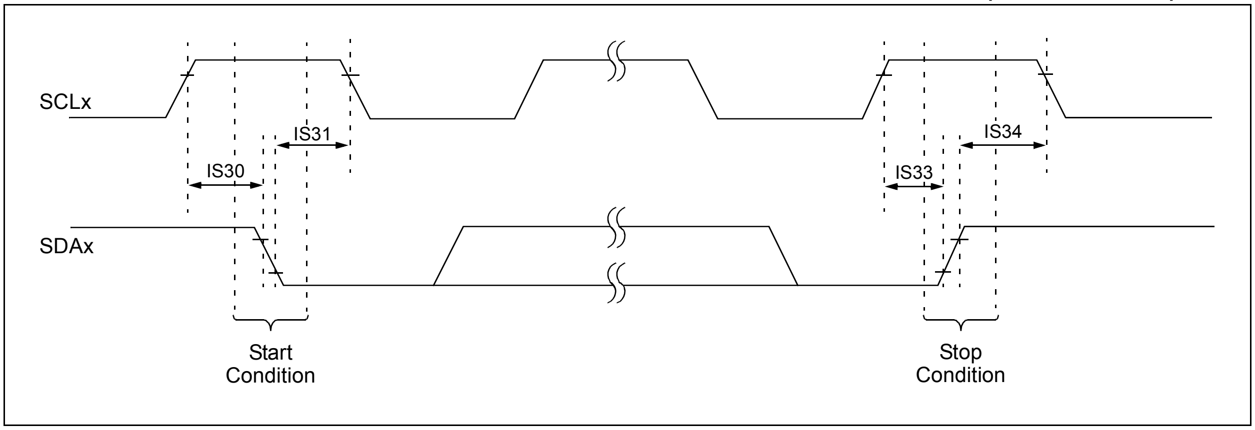


TABLE 29-34: I²C™ BUS START/STOP BITS TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C (Industrial) -40°C ≤ TA ≤ +125°C (Extended)			
Param No.	**Symbol**	**Characteristic**		**Min**	**Max**	**Units**	**Conditions**
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	μs	
			1 MHz mode(1)	0.25	—	μs	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
			1 MHz mode(1)	0.25	—	μs	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	μs	
			400 kHz mode	0.6	—	μs	
			1 MHz mode(1)	0.6	—	μs	
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	
			400 kHz mode	600	—	ns	
			1 MHz mode(1)	250	—	ns	

Note 1: Maximum pin capacitance = 10 pF for all I²C™ pins (for 1 MHz mode only).

FIGURE 29-18: SPIx MODULE MASTER MODE TIMING CHARACTERISTICS (CKE = 0)

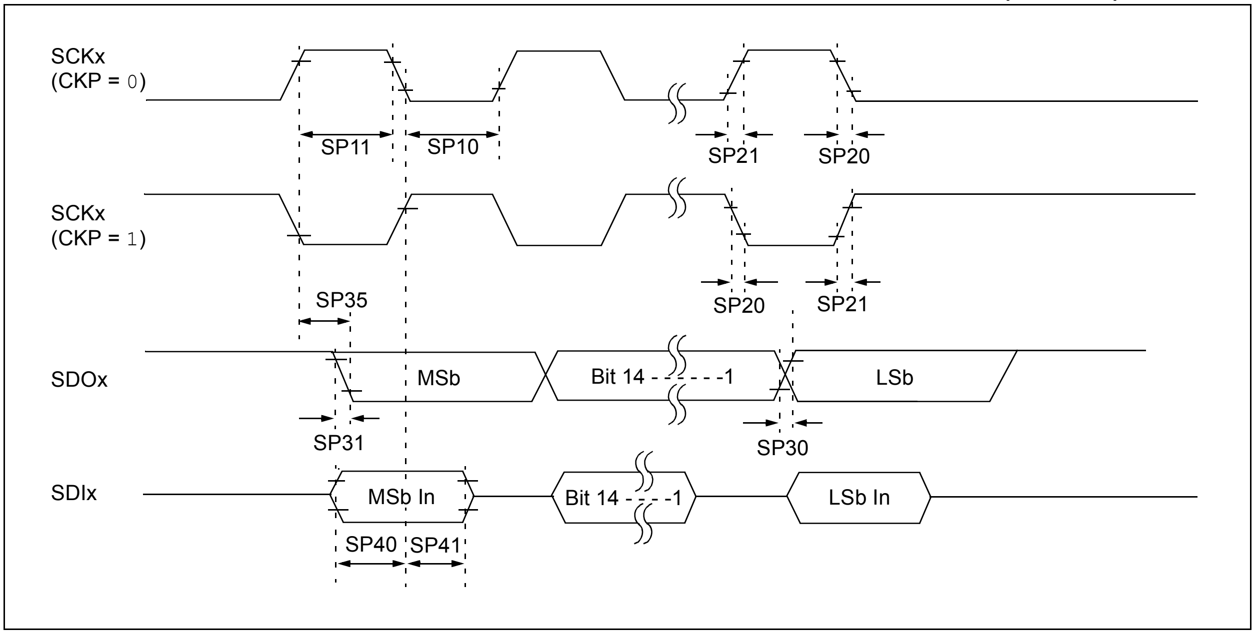


TABLE 29-36: SPIx MASTER MODE TIMING REQUIREMENTS (CKE = 0)

AC CHARACTERISTICS			**Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C (Industrial) -40°C ≤ TA ≤ +125°C (Extended)				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time(2)	TCY/2	—	—	ns	
SP11	TscH	SCKx Output High Time(2)	TCY/2	—	—	ns	
SP20	TscF	SCKx Output Fall Time(3)	—	10	25	ns	
SP21	TscR	SCKx Output Rise Time(3)	—	10	25	ns	
SP30	TdoF	SDOx Data Output Fall Time(3)	—	10	25	ns	
SP31	TdoR	SDOx Data Output Rise Time(3)	—	10	25	ns	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The minimum clock period for SCKx is 100 ns; therefore, the clock generated in Master mode must not violate this specification.

3: This assumes a 50 pF load on all SPIx pins.

FIGURE 30-9: TYPICAL AND MAXIMUM IIDLE vs. TEMPERATURE (FRC MODE)

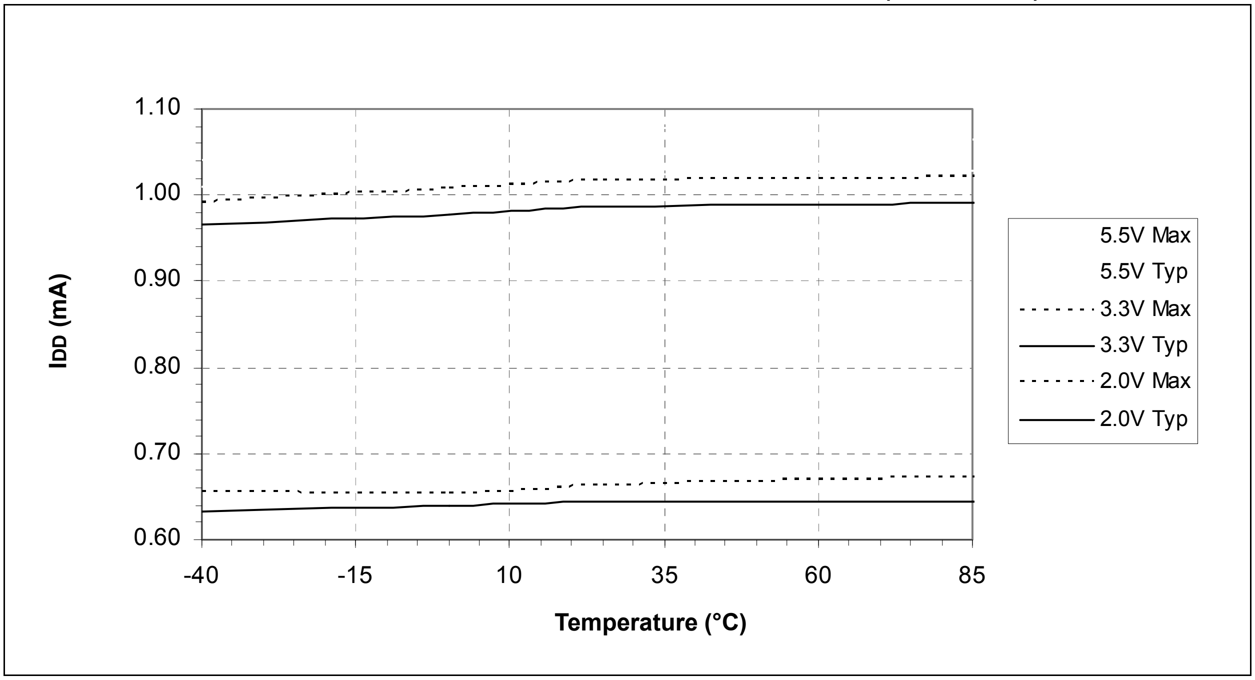


FIGURE 30-22: TYPICAL ΔIDSWDT vs. VDD

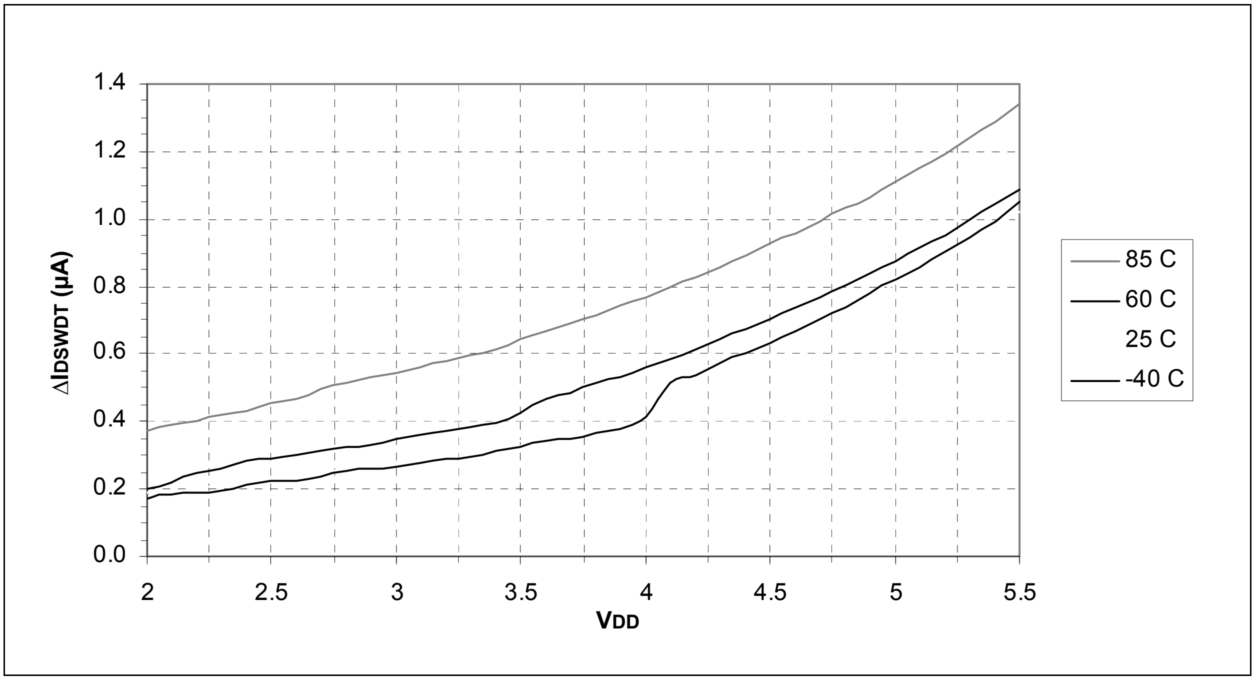
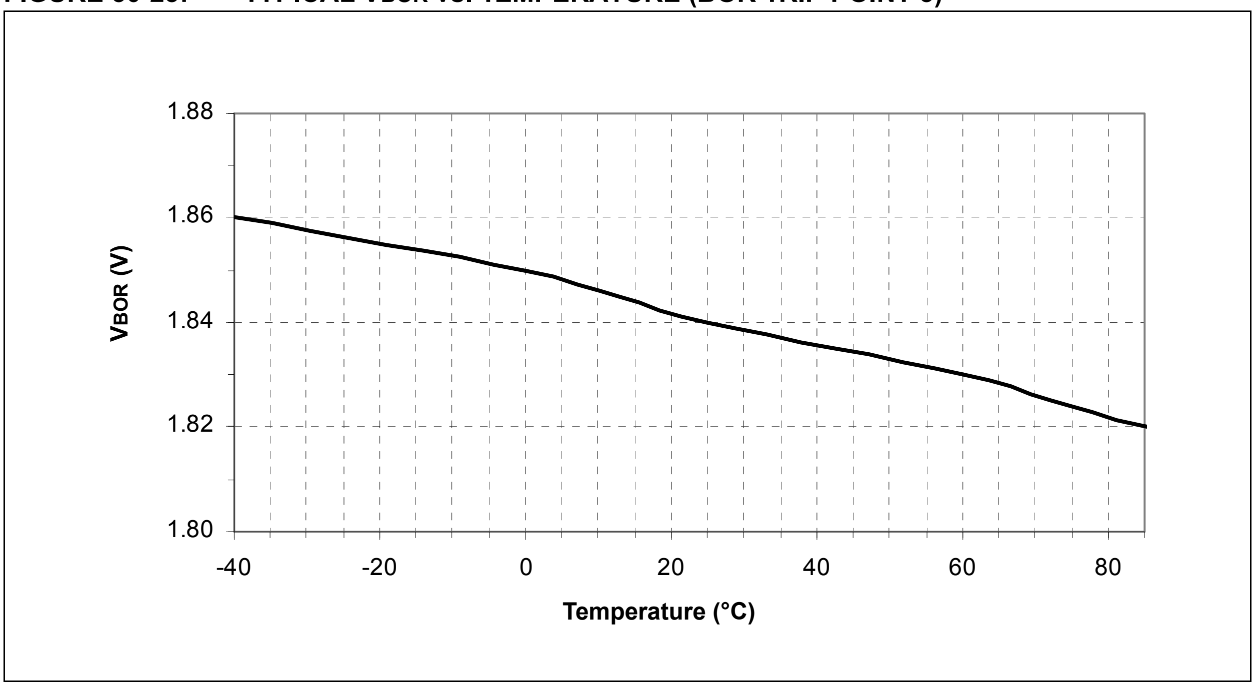
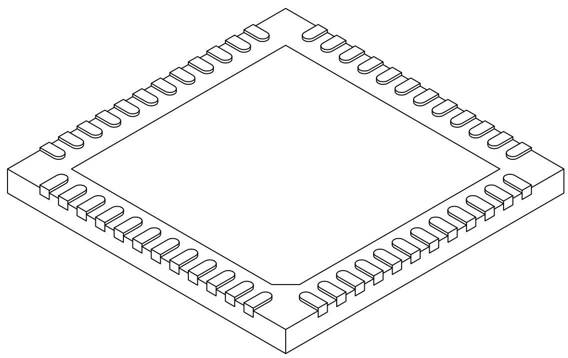


FIGURE 30-23: TYPICAL VBOR vs. TEMPERATURE (BOR TRIP POINT 3)



48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		48	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.45	4.60	4.75
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.45	4.60	4.75
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-153A Sheet 2 of 2

M

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